National Semiconductor

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MM54HC164/MM74HC164
8-Bit Serial-in/Parallel-out Shift Register

General Description

The MM54HC164/MM74HC164 utilizes advanced silicon-gate CMOS technology. It has the high noise immunity and low consumption of standard CMOS integrated circuits. It also offers speeds comparable to low power Schottky devices.

This 8-Bit shift register has gated serial inputs and CLEAR. Each register bit is a D-type master/slave flip flop. Inputs A & B permit complete control over the incoming data. A low at either or both inputs inhibits entry of new data and resets the first flip flop to the low level at the next clock pulse. A high level on one input enables the other input which will then determine the state of the first flip flop. Data at the serial inputs may be changed while the clock is high or low, but only information meeting the setup and hold time requirements will be entered. Data is serially shifted in and out of the 8-Bit register during the positive going transition of the clock pulse. Clear is independent of the clock and accomplished by a low level at the CLEAR input.

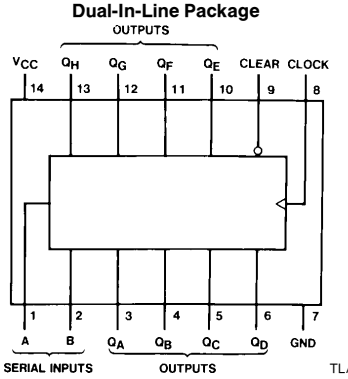
The 54HC/74HC logic family is functionally as well as pin-out compatible with the standard 54LS/74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

Features

- Typical operating frequency: 50 MHz
- Typical propagation delay: 19 ns (clock to Q)
- Wide operating supply voltage range: 2–6V
- Low input current: 1 μA maximum
- Low quiescent supply current: 80 μA maximum (74HC Series)
- Fanout of 10 LS-TTL loads

Connection and Logic Diagrams

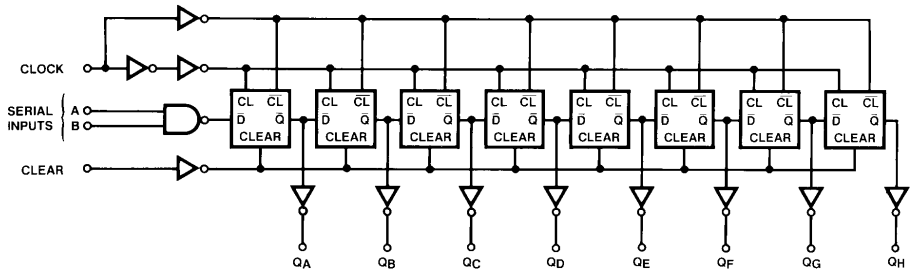
Dual-In-Line Package



TL/F/5315–1

Top View

Order Number MM54HC164 or MM74HC164



TL/F/5315–2

Truth Table

Inputs				Outputs			
Clear	**Clock**	**A**	**B**	Q_A	Q_B	...	Q_H
L	X	X	X	L	L		L
H	L	X	X	Q_{AO}	Q_{BO}		Q_{HO}
H	↑	H	H	H	Q_{An}		Q_{Gn}
H	↑	L	X	L	Q_{An}		Q_{Gn}
H	↑	X	L	L	Q_{An}		Q_{Gn}

H = High Level (steady state), L = Low Level (steady state)

X = Irrelevant (any input, including transitions)

↑ = Transition from low to high level.

Q_{AO}, Q_{BO}, Q_{HO} = the level of Q_A, Q_B, or Q_H, respectively, before the indicated steady state input conditions were established.

Q_{An}, Q_{Gn} = The level of Q_A or Q_G before the most recent ↑ transition of the clock; indicated a one-bit shift.

RRD-B30M105/Printed in U. S. A.

Absolute Maximum Ratings (Notes 1 & 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (V_{CC})	−0.5 to +7.0V
DC Input Voltage (V_{IN})	−1.5 to V_{CC} +1.5V
DC Output Voltage (V_{OUT})	−0.5 to V_{CC} +0.5V
Clamp Diode Current (I_{IK}, I_{OK})	±20 mA
DC Output Current, per pin (I_{OUT})	±25 mA
DC V_{CC} or GND Current, per pin (I_{CC})	±50 mA
Storage Temperature Range (T_{STG})	−65°C to +150°C
Power Dissipation (P_D)	
(Note 3)	600 mW
S.O. Package only	500 mW
Lead Temp. (T_L)	
(Soldering 10 seconds)	260°C

Operating Conditions

		Min	Max	Units
Supply Voltage (V_{CC})		2	6	V
DC Input or Output Voltage (V_{IN}, V_{OUT})		0	V_{CC}	V
Operating Temp. Range (T_A)				
MM74HC		−40	+85	°C
MM54HC		−55	+125	°C
Input Rise or Fall Times				
(t_r, t_f)	V_{CC} = 2.0V		1000	ns
	V_{CC} = 4.5V		500	ns
	V_{CC} = 6.0V		400	ns

DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	V_{CC}	T_A = 25°C	74HC T_A = −40 to 85°C	54HC T_A = −55 to 125°C	Units
				Typ	Guaranteed Limits		
V_{IH}	Minimum High Level Input Voltage		2.0V		1.5	1.5	1.5	V
			4.5V		3.15	3.15	3.15	V
			6.0V		4.2	4.2	4.2	V
V_{IL}	Maximum Low Level Input Voltage**		2.0V		0.5	0.5	0.5	V
			4.5V		1.35	1.35	1.35	V
			6.0V		1.8	1.8	1.8	V
V_{OH}	Minimum High Level Output Voltage	V_{IN} = V_{IH} or V_{IL} $\|I_{OUT}\| \le 20\ \mu A$	2.0V	2.0	1.9	1.9	1.9	V
			4.5V	4.5	4.4	4.4	4.4	V
			6.0V	6.0	5.9	5.9	5.9	V
		V_{IN} = V_{IH} or V_{IL} $\|I_{OUT}\| \le 4.0$ mA	4.5V	4.2	3.98	3.84	3.7	V
		$\|I_{OUT}\| \le 5.2$ mA	6.0V	5.7	5.48	5.34	5.2	V
V_{OL}	Maximum Low Level Output Voltage	V_{IN} = V_{IH} or V_{IL} $\|I_{OUT}\| \le 20\ \mu A$	2.0V	0	0.1	0.1	0.1	V
			4.5V	0	0.1	0.1	0.1	V
			6.0V	0	0.1	0.1	0.1	V
		V_{IN} = V_{IH} or V_{IL} $\|I_{OUT}\| \le 4.0$ mA	4.5V	0.2	0.26	0.33	0.4	V
		$\|I_{OUT}\| \le 5.2$ mA	6.0V	0.2	0.26	0.33	0.4	V
I_{IN}	Maximum Input Current	V_{IN} = V_{CC} or GND	6.0V		±0.1	±1.0	±1.0	μA
I_{CC}	Maximum Quiescent Supply Current	V_{IN} = V_{CC} or GND I_{OUT} = 0 μA	6.0V		8.0	80	160	μA

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: −12 mW/°C from 65°C to 85°C; ceramic "J" package: −12 mW/°C from 100°C to 125°C.

Note 4: For a power supply of 5V ±10% the worst case output voltages (V_{OH}, and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at V_{CC} = 5.5V and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN}, I_{CC}, and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

**V_{IL} limits are currently tested at 20% of V_{CC}. The above V_{IL} specification (30% of V_{CC}) will be implemented no later than Q1, CY'89.

AC Electrical Characteristics $V_{CC} = 5V$, $T_A = 25°C$, $C_L = 15$ pF, $t_r = t_f = 6$ ns

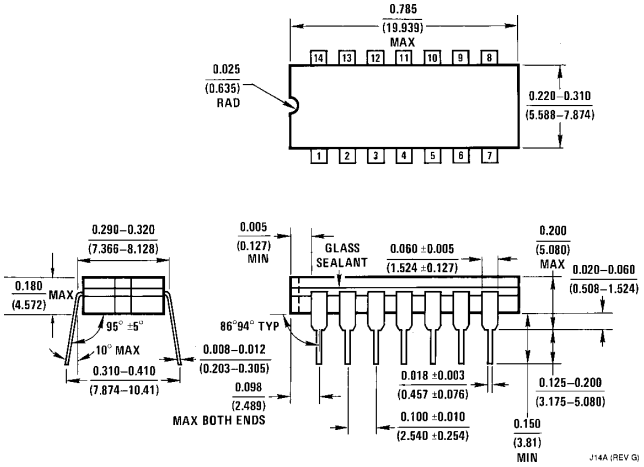
Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
f_{MAX}	Maximum Operating Frequency			30	MHz
t_{PHL}, t_{PLH}	Maximum Propagation Delay, Clock to Output		19	30	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay, Clear to Output		23	35	ns
t_{REM}	Minimum Removal Time, Clear to Clock		−2	0	ns
t_S	Minimum Setup Time Data to Clock		12	20	ns
t_H	Minimum Hold Time Clock to Data		1	5	ns
t_W	Minimum Pulse Width Clear or Clock		10	16	ns

AC Electrical Characteristics $C_L = 50$ pF, $t_r = t_f = 6$ ns (unless otherwise specified)

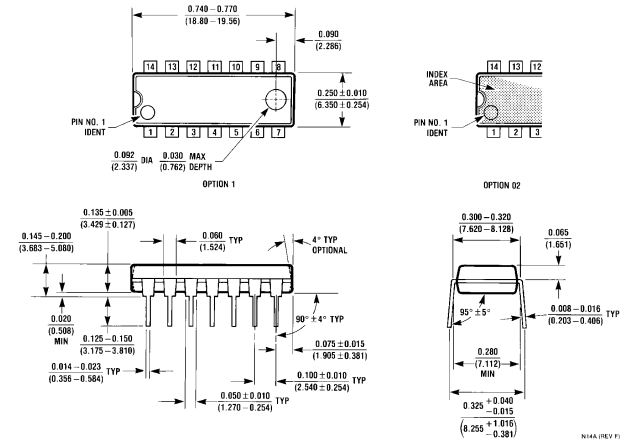
Symbol	Parameter	Conditions	V_{CC}	$T_A = 25°C$	74HC $T_A = -40$ to $85°C$	54HC $T_A = -55$ to $125°C$	Units
				Typ	Guaranteed Limits		
f_{MAX}	Maximum Operating Frequency		2.0V 4.5V 6.0V		5 27 31	4 21 24	3 18 20	MHz MHz MHz
t_{PHL}, t_{PLH}	Maximum Propagation Delay, Clock to Output		2.0V 4.5V 6.0V	115 13 20	175 35 30	218 44 38	254 51 44	ns ns ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay, Clear to Output		2.0V 4.5V 6.0V	140 28 24	205 41 35	256 51 44	297 59 51	ns ns ns
t_{REM}	Minimum Removal Time Clear to Clock		2.0V 4.5V 6.0V	−7 −3 −2	0 0 0	0 0 0	0 0 0	ns ns ns
t_S	Minimum Setup Time Data to Clock		2.0V 4.5V 6.0V	25 14 12	100 20 17	125 25 21	150 30 25	ns ns ns
t_H	Minimum Hold Time Clock to Data		2.0V 4.5V 6.0V	−2 0 1	5 5 5	5 5 5	5 5 5	ns ns ns
t_W	Minimum Pulse Width Clear or Clock		2.0V 4.5V 6.0V	22 11 10	80 16 14	100 20 18	120 24 20	ns ns ns
t_{THL}, t_{TLH}	Maximum Output Rise and Fall Time		2.0V 4.5V 6.0V		75 15 13	95 19 16	110 22 19	ns ns ns
t_r, t_f	Maximum Input Rise and Fall Time		2.0V 4.5V 6.0V		1000 500 400	1000 500 400	1000 500 400	ns ns ns
C_{PD}	Power Dissipation Capacitance (Note 5)	(per package)	5.0V	150				pF
C_{IN}	Maximum Input Capacitance			5	10	10	10	pF

Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.

Physical Dimensions inches (millimeters)



Ceramic Dual-In-Line Package (J)
Order Number MM54HC164J or MM74HC164J
NS Package Number J14A



Molded Dual-In-Line Package (N)
Order Number MM74HC164N
NS Package Number N14A

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